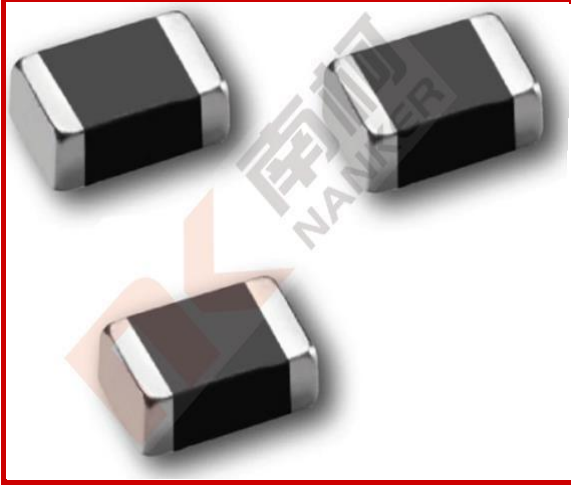


高频磁珠

Ferrite Bead (EMI High Frequency)



特性

Characteristics

修改的内部布局增加了有效抑制范围

Modified internal layout increases the effective suppression range

SMD型，适用于回流焊和波峰焊

SMD Type & suitable for reflow and wave soldering

工作温度：-55°C至+125°C

Operating temperature: -55 °C to +125 °C

应用

Application

特别是用于抑制高频范围内的信号线

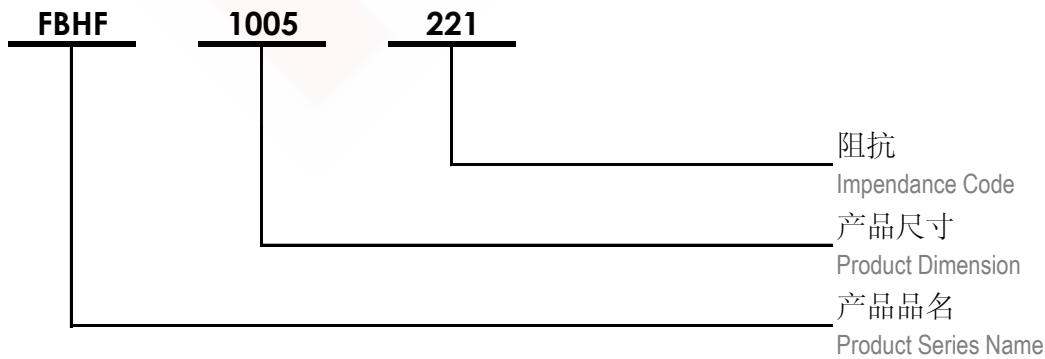
Especially for the suppression of signal lines in the high frequency

用于快速数据线：CPU、高速总线系统、HDD

For fast data lines: CPU, High Speed bus systems, HDD

产品品名介绍

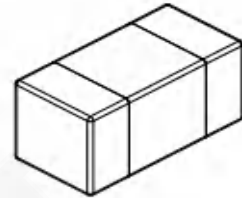
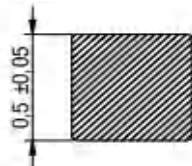
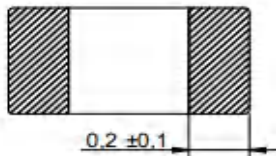
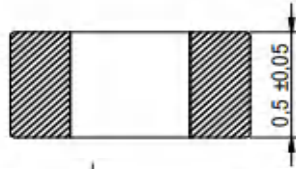
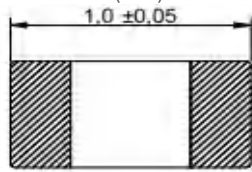
Product Number Structure





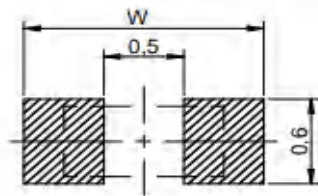
尺寸

Dimension (mm)



焊盘推荐

Land Pattern Recommended (mm)



WIDE BAND / HIGH SPEED: W = 1.5
HIGH CURRENT: W = 2.2



示意图

Schematics



电性特性

Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω)	温升电流 Rated Current I _R 40°C (mA)	直流电阻 DC Resistance DCR _{max} (Ω)	卷盘数量 Taping Reel Qty. pcs
FBHF1005-221	220 ±25%	800	0.250	10,000
FBHF1005-601	600 ±25%	250	0.820	
FBHF1005-102	1,000 ±25%	250	0.900	

测试状态

Test Condition

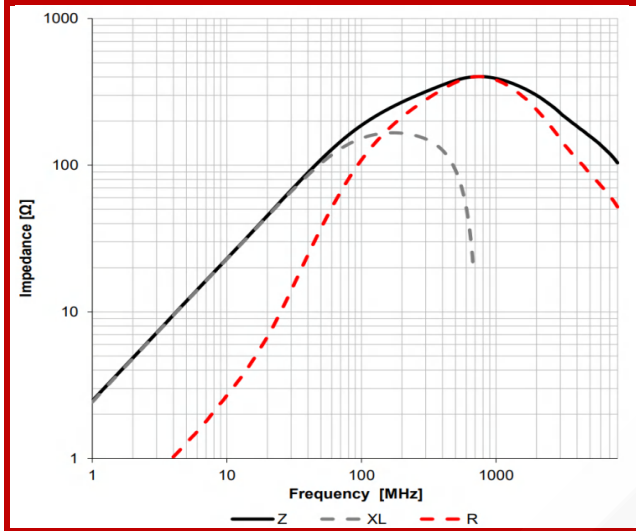
- ☆ 阻抗测试条件为 100MHz (25°C)
Impedance measure condition at 100MHz (25°C)
- ☆ 工作温度: -55°C ~ +125°C
Operating Temperature: -55°C ~ +125°C



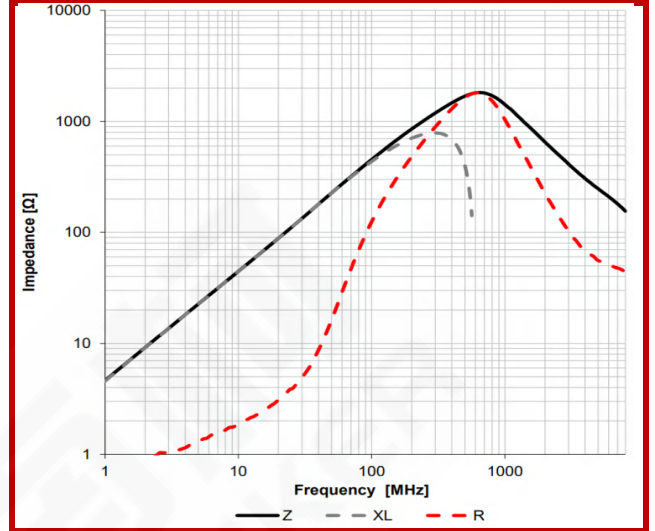
典型阻抗特性

Typical Impedance Characteristics

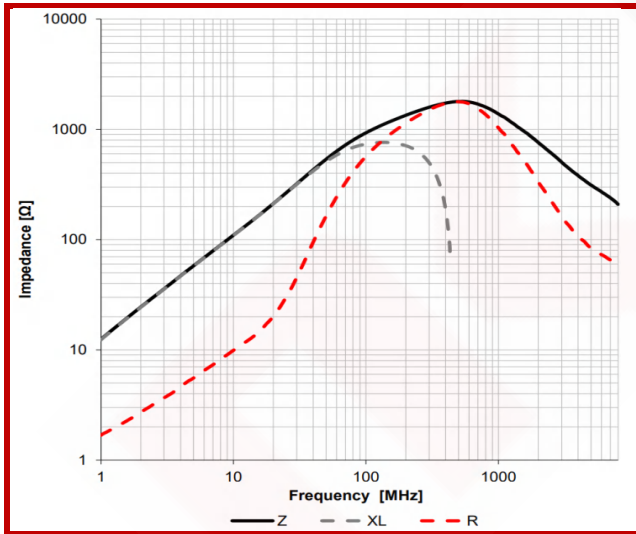
FBHF1005-221



FBHF1005-601



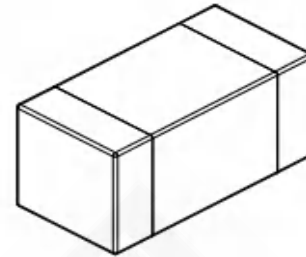
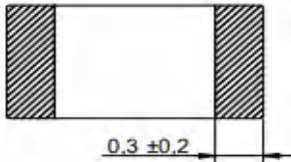
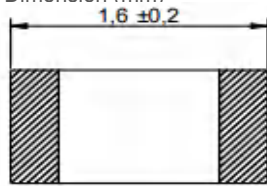
FBHF1005-102





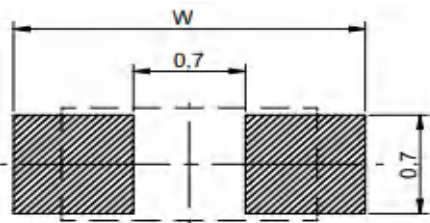
尺寸

Dimension (mm)



焊盘推荐

Land Pattern Recommended (mm)



WIDE BAND / HIGH SPEED: W = 2,2
HIGH CURRENT: W = 2,6



示意图

Schematics



电性特性

Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω)	温升电流 Rated Current I _R 40°C (mA)	直流电阻 DC Resistance DCR _{max} (Ω)	卷盘数量 Taping Reel Qty. pcs
FBHF1608-181	180 ±25%	700	0.250	4,000
FBHF1608-221	220 ±25%	1,300	0.130	
FBHF1608-471	470 ±25%	750	0.190	
FBHF1608-601	600 ±25%	500	0.270	
FBHF1608-102	1,000 ±25%	300	1.200	

测试状态

Test Condition

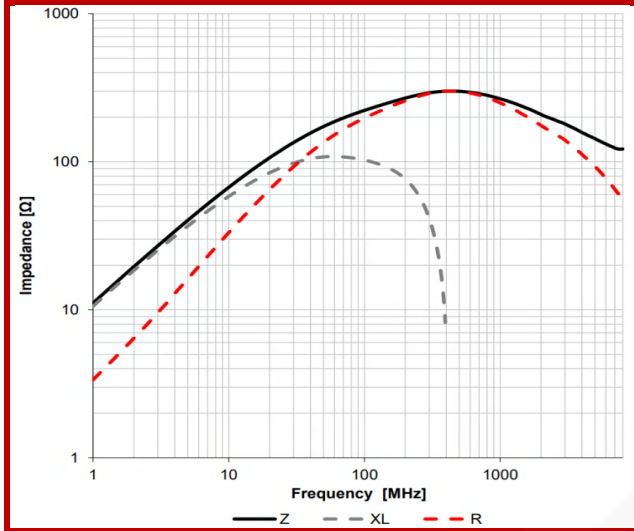
- ☆ 阻抗测试条件为 100MHz (25°C)
Impedance measure condition at 100MHz (25°C)
- ☆ 工作温度: -55°C ~ +125°C
Operating Temperature: -55°C ~ +125°C



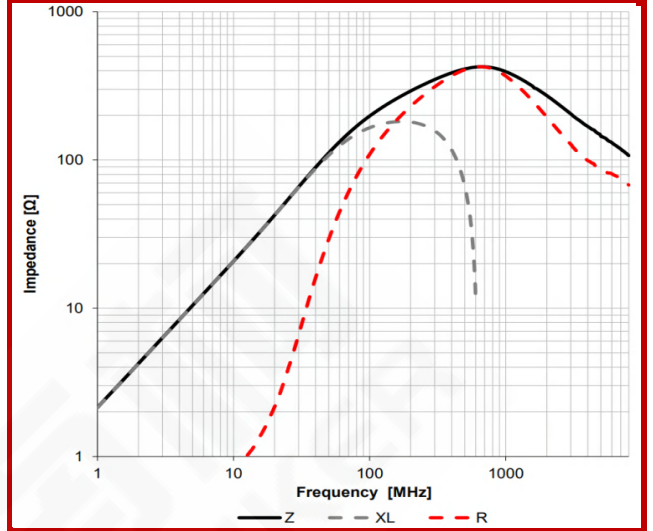
典型阻抗特性

Typical Impedance Characteristics

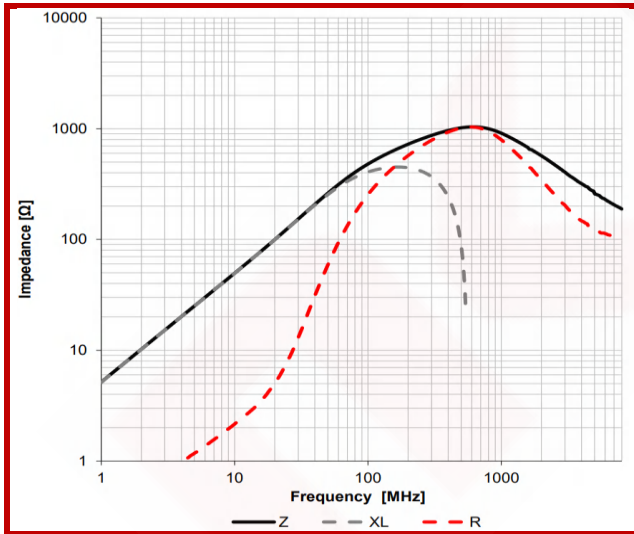
FBHF1608-181



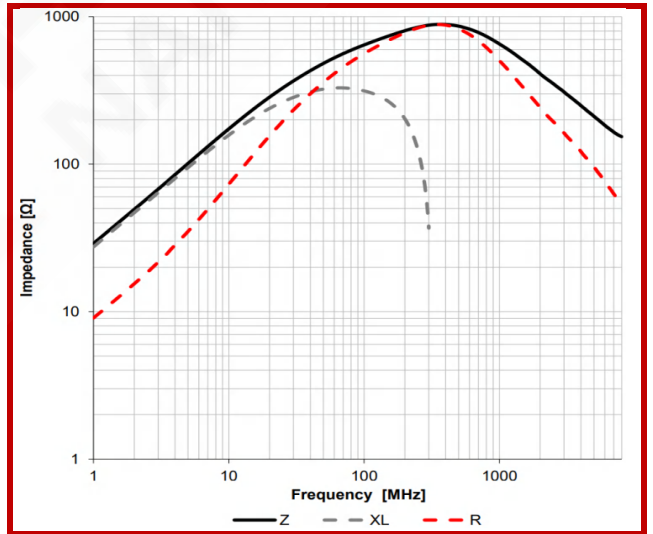
FBHF1608-181



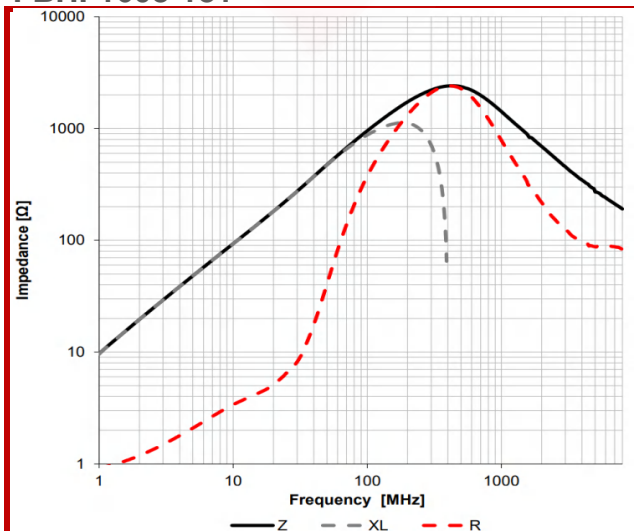
FBHF1608-181



FBHF1608-181



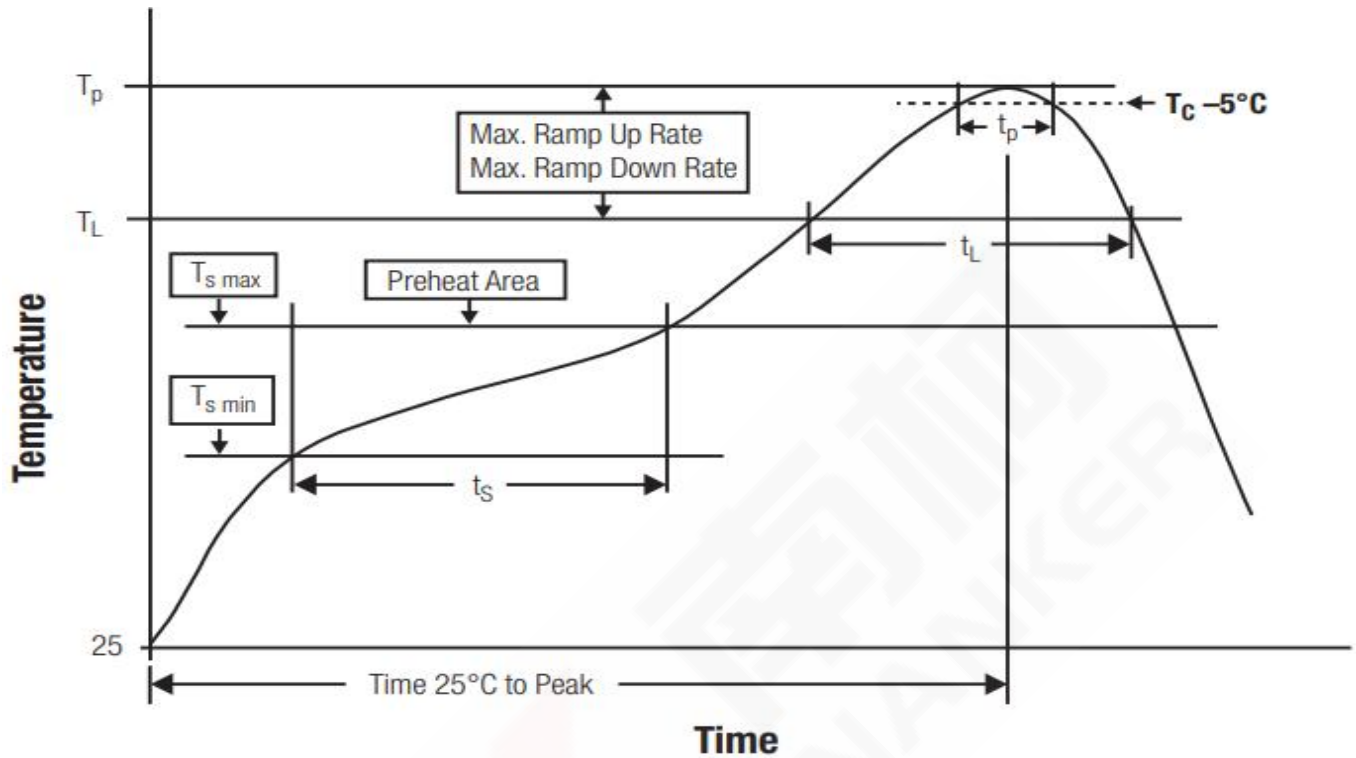
FBHF1608-181





回流焊曲线图

Classification Reflow Profile for SMT Components



封装体峰值温度(Tp)分类

Classification Reflow Soldering Profile:

	封装厚度 Package Thickness	封装体积 Package Volume		
		<350 mm ³	350~2,000 mm ³	>2,000 mm ³
无铅装配 PB-Free Assembly	<1.60mm	260°C	260°C	260°C
	1.60~2.50mm	260°C	250°C	245°C
	>2.50mm	260°C	245°C	245°C

- ◆ 回流焊参照标准 IPC/JEDEC J-STD-020D。
Reflow is refer to standard IPC/JEDEC J-STD-020D.